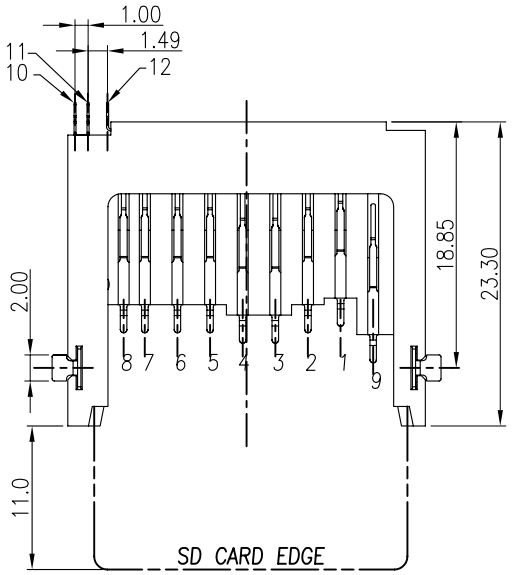
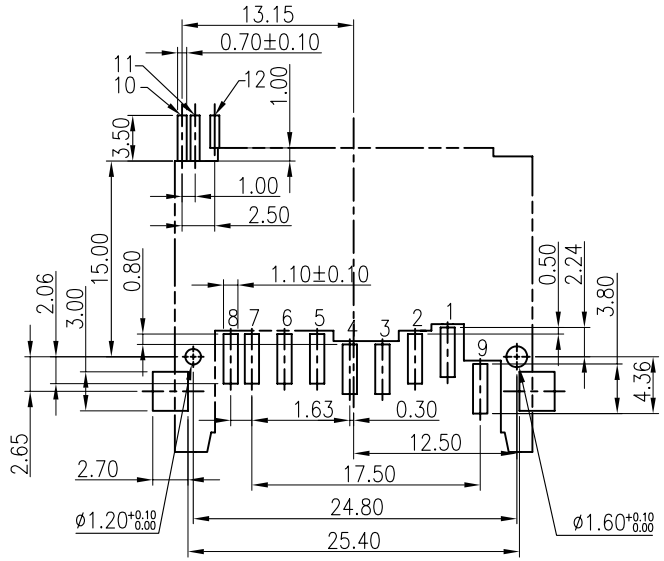
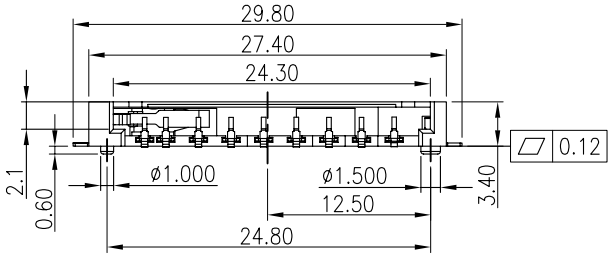
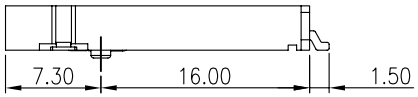




P.C.B Layout



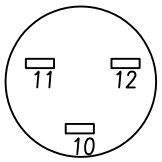


SD CARD PIN DESIGN

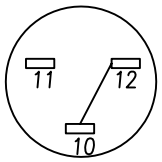
Pin No.	Name	Description
1#	CD/DAT3	Card detect/Data I/O
2#	CMD	Command
3#	VSS1	Ground
4#	VDD	Power
5#	CLK	Clock
6#	VSS2	Ground
7#	DAT0	Data I/O
8#	DAT1	Data I/O
9#	DAT2	Data I/O

NOTES:
1.MATERIAL
HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
CONTACT: COPPER ALLOY.
SHELL: COPPER ALLOY.
2.PLATING
CONTACT AREA: GOLD FLASH PLATED OVER Ni.
SOLDER TAIL: 100 u" MIN Sn PLATED OVER Ni
SHELL SOLDER AREA: GOLD PLATED OVER Ni.
3.RATING
CURRENT RATING: 0.5A
VOLTAGE RATING: 250VRMS
OPERATING TEMPERATURE:-25°C~90°C
4.SPECIFICATION
CONTACT RESISTANCE: 40 MilliOHMS
DIELECTRIC WITHSTANDING VOLTAGE: 500VAC MegOHMS
INSULATION RESISTANCE: 100 MegOHMS
INSERTION FORCE: 40N MAX.
SEPARATION FORCE: 2N MIN.
5.UNSPECIFIED TOLERANCE: .XXX ±0.10
.XX ±0.25
.X ±0.38

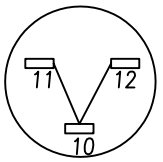
RoHS Compliant



WITHOUT CARD



CARD INSERTED
WRITE PROTWCT:LOCK



CARD INSERTED
WRITE PROTECT:UNLOCK

10--WRITE PROTECT PIN
11--COMMON PIN
12--CARD DETECT PIN

XMULTIPLE
CONNECTING THE INFORMATION AGE

XMULTIPLE ASIA
4F, No. 347,Yang Guang St.,
Neihu Chiu , Taipei , Taiwan 11475

XMULTIPLE USA
543 Country Club Drive #B 128
Simi Valley, CA 93065

CUSTOMER/NO:

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWG NO: XSDC-0-09M1-K000-00-Q

TITLE: SECURE DIGITAL MEMORY CARD CONNECTOR, NORMAL TYPE

DRAWN: LEON

PART NO: XSDC-0-09M1-K000-00-Q

CHKD: JEFF

DIMENSIONS	SHEET	REV
mm[inch]	1 of 1	01

DATE: 09/08/05